

IN THE SPECIFICATION

Please amend the specification as follows:

Please add the new paragraphs beginning at page 2, line 21, as follows:

FIG. 9 is a section view of the example semiconducting device shown in FIG. 1 taken along line 9-9.

FIG. 10 is a section view of the example semiconducting device shown in FIG. 4 taken along line 10-10.

The paragraph beginning at page 3, line 22, is amended as follows:

As shown in FIGS. 2-4, semiconducting device 10 may include a plurality of contacts 26 that are each attached to the first surface 24 of interposer 16 at first section 20 and second section 22. In some embodiments, fold 18 is on one side of first die 12 and at least one of the contacts 26 is on an opposing side of first die 12 (FIGS. 1 and 2). In other embodiments, at least one of the contacts 26 is on some, or all, sides of first die 12. FIG. 9 shows an example semiconducting device 10 where at least one of the contacts 26 is on three sides of the first die 12 while FIG. 10 shows an example semiconducting device 10 where at least one of the contacts 26 is on each side of the first die 12. In FIGS. 3 and 4, contacts 26 are visible on only two sides of first die 12 because of the orientation of the FIGS.